Attorney Docket No. 81872.0052 Customer No. 26021

Appl. No. 10/650,504 Amdt. Dated March 15, 2007 Reply to Office Action of December 15, 2006

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-12. (Canceled)

 (Currently amended): A dry-etching-method for producing a solar cell, etching a surface of a substrate to be etched, said-method comprising;

placing a substrate <u>for a solar cell</u> to be etched on an electrode inside a chamber; wherein a part of said chamber is connected to a ground; and

covering said substrate to be etched with a plate between said part of said chamber and said electrode, wherein said plate is provided with a number of opening portions; and [[,]]

forming textures on a surface of the substrate by using residues being chiefly composed of components of the substrate as an etching mask, wherein a distance between <u>said substrate and</u> a surface of <u>said plate</u> opposing said substrate to be etched and said substrate to be etched in a peripheral portion of said plate is set shorter than a distance between <u>said substrate and</u> said surface opposing said substrate to be etched and said surface opposing said substrate to be etched in a central portion of said plate.

14. (Currently amended): The dry etching method for producing a solar cell according to claim 13, wherein said textures are formed by dry etching method is a reactive ion etching method.

15-19. (Canceled)

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(Currently amended): A dry etching method for producing a solar cell,
 etching a surface of a substrate to be etched, said method comprising:

placing a substrate <u>for a solar cell</u> to be etched on an electrode inside a chamber; wherein a part of said chamber is connected to a ground,

covering said substrate to be etched with a plate provided with a number of opening portions; and

forming fine textures on a surface of said substrate to-be-etched <u>using</u> residues being chiefly composed of components of the substrate as an etching mask, by applying RF power to said electrode,

wherein <u>said plate is provided with</u> a protruding wall is provided to said plate
on a surface opposing said substrate to be etched and said protruding wall is
separated from a nearest surface of said substrate by a space.

21. (Original): The dry-etching method for producing a solar cell according to claim 20, wherein said textures are formed by dry-etching method is a reactive ion etching method.

22-23. (Canceled)

- 24. (New): The method for producing a solar cell according to Claim 13, wherein said plate is provided with a protruding wall on a surface thereof opposing said substrate and said protruding wall is separated from a nearest surface thereof opposing said substrate and said protruding wall is separated from a nearest surface of said substrate by a space.
- 25. (New): The method for producing a solar cell according to Claim 20, wherein a lower end portion of said protruding wall abuts on said electrode.

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26. (New): The method for producing a solar cell according to Claim 20, wherein the substrate for a solar cell is a silicon substrate.